What is claimed is:

[Claim 1] 1. A printed circuit board (PCB) comprising:

a plastic substrate; and
a circuit layout formed on the plastic substrate, having a first layout and a second layout,
wherein the second layout comprises a pseudo-layout to prevent the PCB from being bent when heated.

[Claim 2] 2. The PCB of claim 1 wherein density of circuits of the second layout has a lower circuit density than that of the first layout.

[Claim 3] 3. The PCB of claim 1 wherein the circuit layout comprises signal traces and power traces, the pseudo-layout is isolated from the signal traces and the power traces on the PCB.

[Claim 4] 4. The PCB of claim 1 wherein the pseudo-layout comprises a plurality of pseudo-traces neither for power nor signal transmission.

[Claim 5] 5. The PCB of claim 3 wherein the pseudo-traces are parallel to each other in a netlike structure.

[Claim 6] 6. The PCB of claim 5 wherein the parallel pseudo-traces having an interval distance, the interval distance is 5mil.

[Claim 7] 7. The PCB of claim 5 wherein the width of the pseudo-traces is 5mil.

[Claim 8] 8. A method for manufacturing a printed circuit board (PCB), the method comprising the steps of:

forming a circuit layout on a PCB substrate, the circuit layout comprising signal lines and power lines; and
installing a pseudo-layout in the circuit layout to prevent the PCB from being bent when the PCB is heated.

[Claim 9] 9. The method of claim 8 wherein the pseudo-layout comprises a plurality of pseudo-traces.

[Claim 10] 10. The method of claim 9 wherein the pseudo-layout is formed on the PCB and is isolated from signal lines and power lines of the circuit layout.

[Claim 11] 11. The method of claim 9 wherein the alignment of the pseudo-traces are parallel.

[Claim 12] 12. The method of claim 11 wherein the pseudo-traces have an interval distance of 5mil.

[Claim 13] 13. The method of claim 8 wherein the width of the pseudo-traces is 5mil.